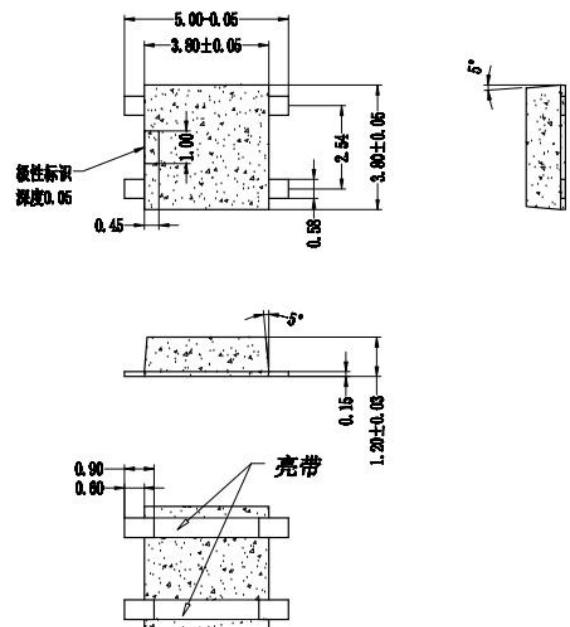


Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering : 260°C/10 seconds at terminals

UMB^F



Dimensions In inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

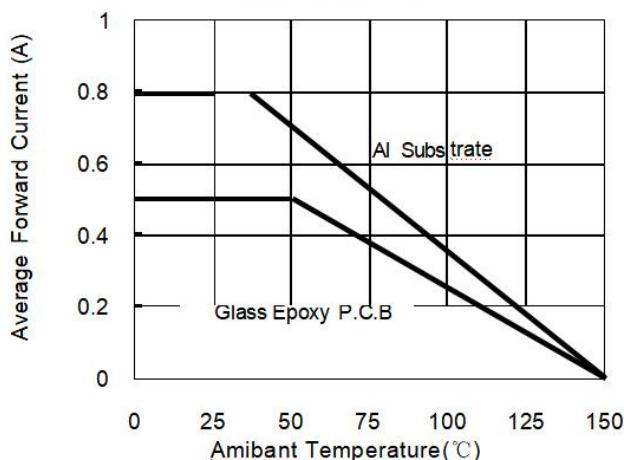
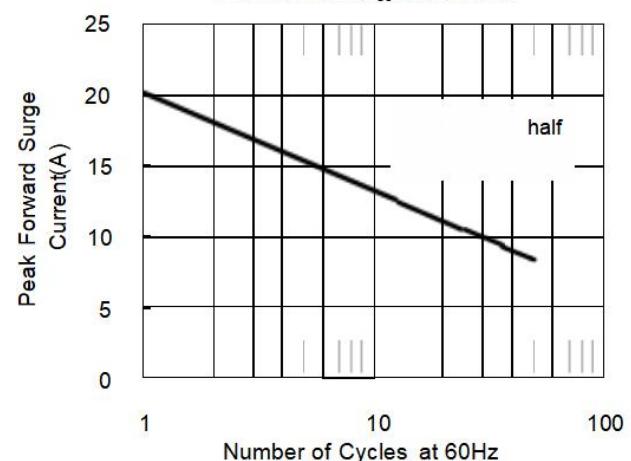
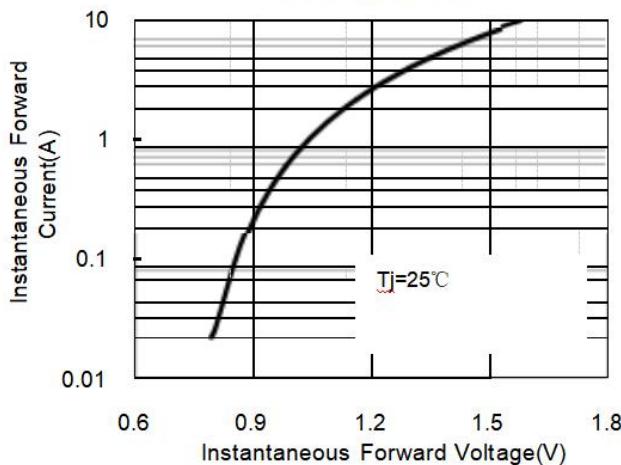
Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Items	Symbol	UMB05F	UMB1F	UMB2F	UMB4F	UMB6F	UMB8F	UMB10F	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _A =50°C -on glass-epoxy P.C.B ⁽¹⁾ - at T _A =30°C on aluminum substrate ⁽²⁾	I _{F(AV)}				0.5				A
0.8									
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}				20				A
Thermal resistance from junction to ambient per leg	R _{θJA} ⁽¹⁾ R _{θJA} ⁽²⁾			100					°C/W
				80					
Thermal resistance from junction to lead per leg ⁽¹⁾	R _{θJL}			30					°C/W
Operating junction and storage temperature range	T _J , T _{STG}			-55 to +150					°C

Note:1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

2.Thermal resistance from junction to ambient and from junction to lead mounted on
P.C.B with 0.5×0.5"(13×13mm)copper pads.

**Fig.1 Forward Current Derating Curve****Fig.2 Maximum Non-Repetitive Peak Forward Surge Current****Fig.3 Typical Instantaneous Forward Characteristics****Fig.4 Typical Reverse Leakage Characteristics**